

**PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION**

**Part Number:** [0901522112](#)  
**Status:** **Active**  
**Overview:** [cgrid\\_sl\\_products](#)  
**Description:** 2.54mm (.100") Pitch C-Grid III™ PC Board Connector, Dual Row, Right Angle, Straight PCB Pins 1.0µm (40µ") Tin (Sn), 12 Circuits

**Documents:**

[3D Model](#) [RoHS Certificate of Compliance \(PDF\)](#)  
[Drawing \(PDF\)](#)

**General**

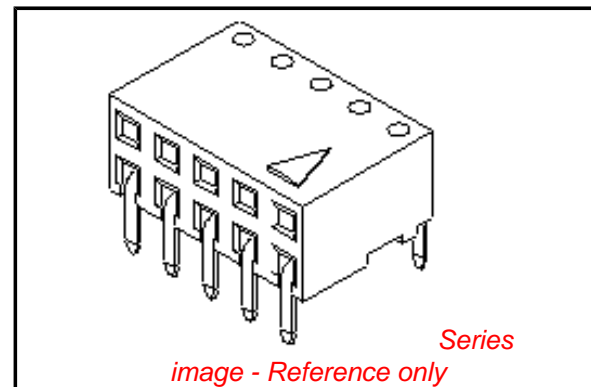
Product Family	PCB Receptacles
Series	<a href="#">90152</a>
Application	Board-to-Board
Overview	<a href="#">cgrid_sl_products</a>
Product Name	C-Grid III™

**Physical**

Circuits (Loaded)	12
Circuits (maximum)	12
Color - Resin	Black
Durability (mating cycles max)	30
Glow-Wire Compliant	No
Guide to Mating Part	No
Keying to Mating Part	None
Lock to Mating Part	No
Material - Metal	Phosphor Bronze
Material - Plating Mating	Tin
Material - Plating Termination	Tin
Material - Resin	Polyester
Number of Rows	2
Orientation	Right Angle
PC Tail Length (in)	0.114 In
PC Tail Length (mm)	2.90 mm
PCB Locator	No
PCB Retention	None
PCB Thickness Recommended (in)	0.063 In
PCB Thickness Recommended (mm)	1.60 mm
Packaging Type	Tube
Pitch - Mating Interface (in)	0.100 In
Pitch - Mating Interface (mm)	2.54 mm
Pitch - Term. Interface (in)	0.100 In
Pitch - Term. Interface (mm)	2.54 mm
Plating min: Mating (µin)	40
Plating min: Mating (µm)	1.00
Plating min: Termination (µin)	40
Plating min: Termination (µm)	1.00
Polarized to Mating Part	Yes
Polarized to PCB	No
Stackable	No
Surface Mount Compatible (SMC)	No
Temperature Range - Operating	-55°C to +125°C
Termination Interface: Style	Through Hole

**Electrical**

Current - Maximum per Contact	3A
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**EU RoHS**

**ELV and RoHS Compliant**  
**REACH SVHC Contains SVHC: No**  
**Halogen-Free Status**  
**Not Reviewed**

**China RoHS**



**Need more information on product environmental compliance?**

Email [productcompliance@molex.com](mailto:productcompliance@molex.com)  
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

**Search Parts in this Series**

[90152Series](#)

**Mates With**

[90122](#) , [90131](#)

Grounding to PCB  
Voltage - Maximum

No  
350V AC/DC

**Solder Process Data**

Lead-free Process Capability

Wave Capable (TH only)

**Material Info**

**Reference - Drawing Numbers**

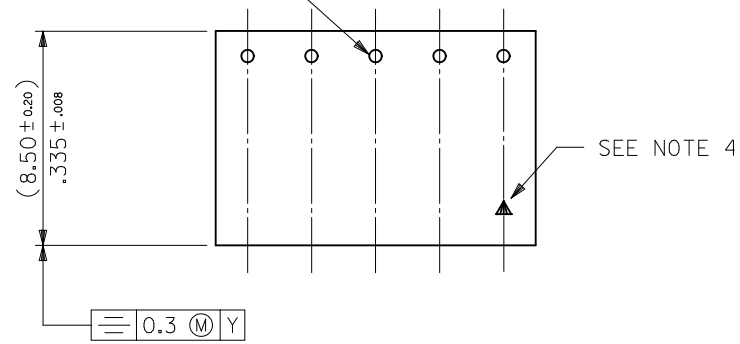
Sales Drawing

SDA-90152

This document was generated on 05/24/2010

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TERMINAL RETENTION FEATURE



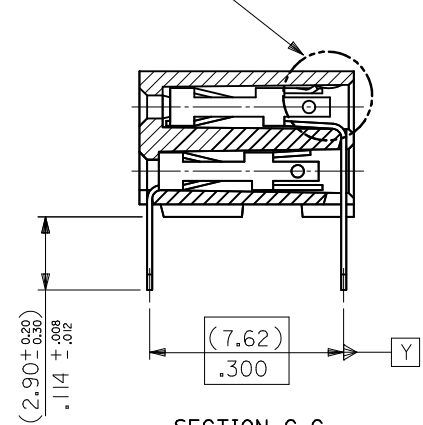
RECOMMENDED P.C. BOARD HOLE PATTERN

NOTES

- 1) CONTACT-PLATED PHOSPHOR BRONZE.
- 2) HOUSING-15% GLASS FILLED POLYESTER. COLOUR-BLACK.
- 3) COMPATABLE WITH PCB HOLE PATTERN.
- 4) THIS MARK INDICATES CIRCUIT NO.1.
- 5) FOR (0.635)/.025 SQ. MALE PINS THE LENGTH MUST BE (5.65)/.222 MIN & (7.00)/.276 MAX. TO ENSURE GOOD CONNECTION WITH CONTACT.
- 6) PRODUCT SPECIFICATION: PS-99020-0001
- 7) RECOMMENDED PCB THICKNESS 1.6MM



SEE DETAIL "A"



SECTION C-C

DETAIL "A"



TERMINAL RETENTION FEATURE

CHG PKG QTY FOR 4CKT EC NO: S2010-0556 DRW:NAT/SEE 2010/01/12 CHKD:SKANG 2010/01/14 APPR:MLONG 2010/01/14	QUALITY SYMBOLS $F_{\Delta} = 0$ $F_{\square} = 0$ $F_{\nabla} = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		mm	INCH	DRAWN BY DB	DATE 1987/07/14	TITLE C-GRID PCB CONN DR HORZ			
B	REV	4 PLACES	± ---	± ---	CHECKED BY DB	DATE 1987/07/14	APPROVED BY MLONG 2010/01/14		
		3 PLACES	± ---	± ---	MATERIAL NO. SEE TABLE		DOCUMENT NO. SDA-90152	SHEET NO. 1 OF 5	
		2 PLACES	± 0.20	± .008	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
		1 PLACE	± ---	± ---					
		ANGULAR ± 2 °							
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							

	10	9	8	7	6	5	4	3	2	1	
	PART NO.	CKT	DIM. A		DIM. B <sup>(+0.00)</sup> <sub>(-0.30)</sub> <sup>+0.00</sup> <sub>-0.12</sub>		PCS/ TUBE				
F	90152-XX04	4	(2.54)	.100	(5.08)	.200	109	PLATING VERSION A			
	06	6	(5.08)	.200	(7.62)	.300	73	PRE-PLATED HOT DIP TIN 1.0 TO 2.5 microns (.00004" TO .00010").			
	08	8	(7.62)	.300	(10.16)	.400	55	PLATING VERSION E			
	10	10	(10.16)	.400	(12.70)	.500	44	1.27 TO 1.78 microns (.00005" TO .00007") NICKEL OVERALL, 0.38 TO 0.64 microns (.000015" TO .000025") GOLD ON CONTACT AREA (OVER NICKEL). 3 TO 5 microns (.00012" TO .00020") TIN ON SOLDER TAILS (OVER NICKEL).			
	12	12	(12.70)	.500	(15.24)	.600	36	PLATING VERSION F			
	14	14	(15.24)	.600	(17.78)	.700	31	1.27 TO 1.78 microns (.00005" TO .00007") NICKEL OVERALL, 0.76 TO 1.0 microns (.00003" TO .00004") GOLD ON CONTACT AREA (OVER NICKEL). 3 TO 5 microns (.00012" TO .00020") TIN ON SOLDER TAILS (OVER NICKEL).			
E	16	16	(17.78)	.700	(20.32)	.800	27	PLATING VERSION G			
	18	18	(20.32)	.800	(22.86)	.900	24	1.27 TO 1.78 microns (.00005" TO .00007") NICKEL OVERALL, 0.125 TO 0.20 microns (.000005" TO .0000079") GOLD ON CONTACT AREA (OVER NICKEL). 3 TO 5 microns (.00012" TO .00020") TIN ON SOLDER TAILS (OVER NICKEL).			
	20	20	(22.86)	.900	(25.40)	1.000	22	90152 - X X Y Y			
	22	22					20	INDICATES NO. OF CIRCUITS			
	24	24	(27.94)	1.100	(30.48)	1.200	18	PLATING CODE. 21 = VERSION A 22 = VERSION E 23 = VERSION F 25 = VERSION G			
	26	26	(30.48)	1.200	(33.02)	1.300	16				
D	28	28					14				
	30	30	(35.56)	1.400	(38.10)	1.500	14				
	32	32					13				
	34	34	(40.64)	1.600	(43.18)	1.700	12				
	36	36	(43.18)	1.700	(45.72)	1.800	12				
	38	38	(45.72)	1.800	(48.26)	1.900	11				
	40	40	(48.26)	1.900	(50.80)	2.000	11				
	42	42					10				
	44	44	(53.34)	2.100	(55.88)	2.200	10				
	46	46					10				
C	48	48					9				
	50	50	(60.96)	2.400	(63.50)	2.500	8				
	52	52					8				
	54	54					8				
	56	56	(68.58)	2.700	(71.12)	2.800	7				
	58	58					7				
B	60	60	(73.66)	2.900	(76.20)	3.000	7				
	62	62					6				
	90152-XX64	64	(78.74)	3.100	(81.28)	3.200	5				

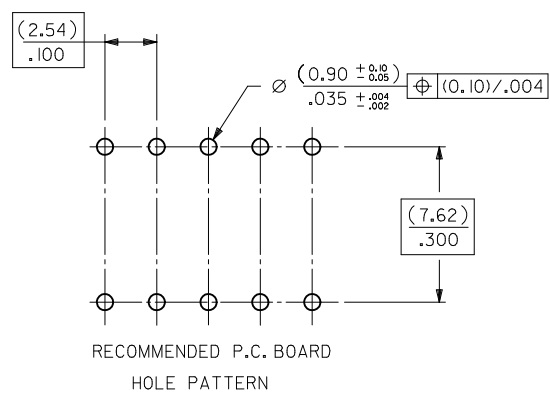
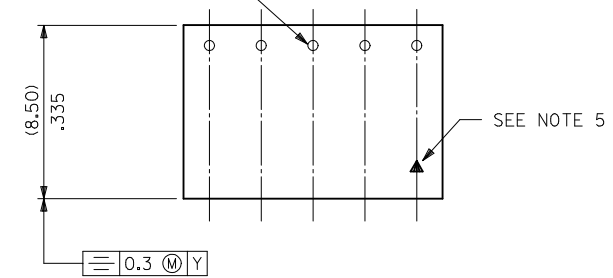
STANDARD PRODUCTS

CHG PKG QTY FOR 4CKT EC NO: S2010-0556 DRWN:ATSEE 2010/01/12 CHKD:SKANG 2010/01/14 APPR:MLONG 2010/01/14	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION															
	$\nabla_A = 0$ $\nabla_C = 0$ $\nabla_P = 0$	<table border="1"> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.20</td> <td>± .008</td> </tr> <tr> <td>1 PLACE</td> <td>± ---</td> <td>± ---</td> </tr> </table>		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.20	± .008	1 PLACE	± ---	± ---	MM ONLY	NTS	METRIC	
		mm	INCH																		
	4 PLACES	± ---	± ---																		
3 PLACES	± ---	± ---																			
2 PLACES	± 0.20	± .008																			
1 PLACE	± ---	± ---																			
DESCRIPTION	ANGULAR ± 2 °	DRAWN BY	DATE	TITLE	C-GRID PCB CONN DR HORZ																
REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DB	1987/07/14	MOLEX INCORPORATED																	
		MLONG	2010/01/14	SEE TABLE	SDA-90152	SHEET NO. 2 OF 5															
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																	

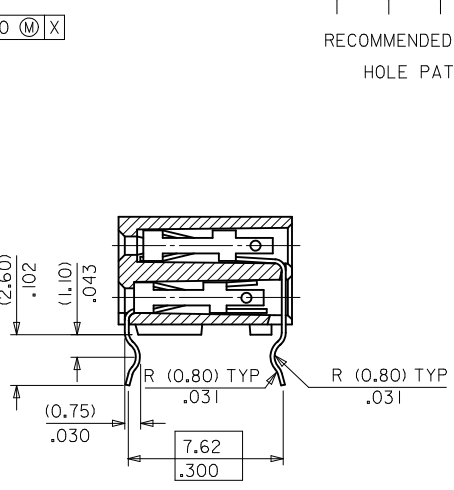
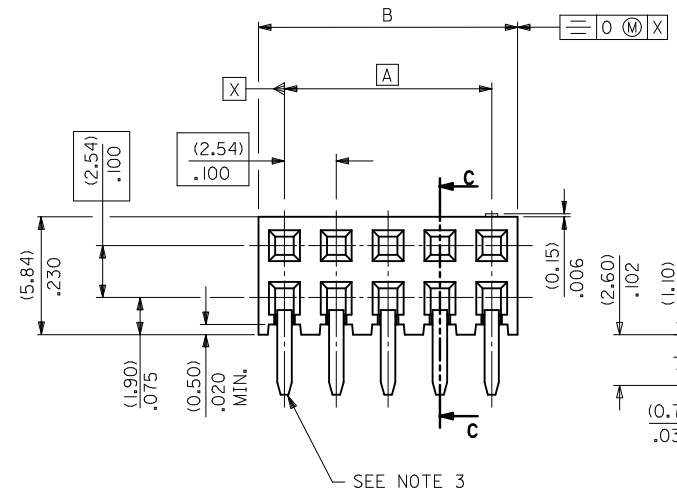


10 9 8 7 6 5 4 3 2 1

TERMINAL RETENTION FEATURE



RECOMMENDED P.C. BOARD HOLE PATTERN

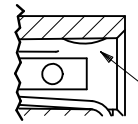


SECTION C-C

NOTES

- 1) CONTACT-PLATED PHOSPHOR BRONZE.
- 2) HOUSING-15% GLASS FILLED POLYESTER, COLOUR-BLACK.
- 3) COMPATIBLE WITH PCB HOLE PATTERN.
- 4) RECOMMENDED PC BOARD THICKNESS (1.4 ± .2) / .055 ± .008
- 5) THIS MARK INDICATES CIRCUIT NO.1.
- 6) FOR (0.635) / .025 SO. MALE PINS THE LENGTH MUST BE (5.65) / .222 MIN & (7.00) / .276 MAX. TO ENSURE GOOD CONNECTION WITH CONTACT.

DETAIL \*A\*



TERMINAL RETENTION FEATURE

CHG PKG QTY FOR 4CKT EC NO: S2010-0556 DRAWN/AT/SEE 2010/01/12 CHKD/SKANG 2010/01/14 APPR/MLONG 2010/01/14	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM ONLY	NTS	METRIC	⊙
	▽=0	4 PLACES ± --- ± ---	DRAWN BY DATE			
	▽=0	3 PLACES ± --- ± ---	DB 1987/07/14	TITLE		

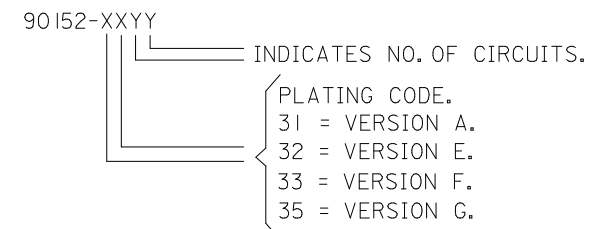
2 PLACES ± .020 ± .008	CHECKED BY DATE		
1 PLACE ± --- ± ---	DB 1987/07/14		
ANGULAR ± 2 °	APPROVED BY DATE		
	MLONG 2010/01/14		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE	SEE TABLE
	A3	

C-GRID PCB CONN DR HORZ	
MOLEX INCORPORATED	
DOCUMENT NO.	SDA-90152
SHEET NO.	3 OF 5

9 8 7 6 5 4 3 2 1

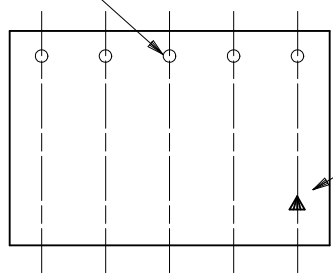
	10	9	8	7	6	5	4	3	2	1	
	PART NO.	CKT	DIM. A		DIM. B <sup>(+0.00/-0.30)</sup> <sub>+0.00/-0.12</sub>		PCS/ TUBE				
F	90152-XX04	4	(2.54)	.100	(5.08)	.200	109		PLATING VERSION A		
	06	6	(5.08)	.200	(7.62)	.300	73		PRE-PLATED HOT DIP TIN 1.0 TO 2.5 microns (.00004" TO .00010").		
	08	8	(7.62)	.300	(10.16)	.400	55		PLATING VERSION E		
	10	10	(10.16)	.400	(12.70)	.500	44		1.27 TO 1.78 microns (.00005" TO .00007") NICKEL OVERALL, 0.38 TO 0.64 microns (.000015" TO .000025") GOLD ON CONTACT AREA (OVER NICKEL). 3 TO 5 microns (.00012" TO .00020") TIN ON SOLDER TAILS (OVER NICKEL).		
	12	12	(12.70)	.500	(15.24)	.600	36		PLATING VERSION F.		
	14	14	(15.24)	.600	(17.78)	.700	31		1.27 TO 1.78 microns (.00005" TO .00007") NICKEL OVERALL, 0.76 TO 1.0 microns (.00003" TO .00004") GOLD ON CONTACT AREA (OVER NICKEL). 3 TO 5 microns (.00012" TO .00020") TIN ON SOLDER TAILS (OVER NICKEL).		
E	16	16	(17.78)	.700	(20.32)	.800	27		PLATING VERSION G.		
	18	18	(20.32)	.800	(22.86)	.900	24		1.27 TO 1.78 microns (.00005" TO .00007") NICKEL OVERALL, 0.125 TO 0.20 microns (.000005" TO .0000079") GOLD ON CONTACT AREA (OVER NICKEL). 3 TO 5 microns (.00012" TO .00020") TIN ON SOLDER TAILS (OVER NICKEL).		
	20	20	(22.86)	.900	(25.40)	1.000	22				
	22	22					20				
	24	24	(27.94)	1.100	(30.48)	1.200	18				
	26	26	(30.48)	1.200	(33.02)	1.300	16				
D	28	28					14				
	30	30	(35.56)	1.400	(38.10)	1.500	14				
	32	32					13				
	34	34	(40.64)	1.600	(43.18)	1.700	12				
	36	36	(43.18)	1.700	(45.72)	1.800	12				
	38	38	(45.72)	1.800	(48.26)	1.900	11				
	40	40	(48.26)	1.900	(50.80)	2.000	11				
	42	42					10				
	44	44	(53.34)	2.100	(55.88)	2.200	10				
	46	46					10				
C	48	48					9				
	50	50	(60.96)	2.400	(63.50)	2.500	8				
	52	52					8				
	54	54					8				
	56	56	(68.58)	2.700	(71.12)	2.800	7				
	58	58					7				
B	60	60	(73.66)	2.900	(76.20)	3.000	7				
	62	62					6				
	90152-XX64	64	(78.74)	3.100	(81.28)	3.200	5				



A	CHG PKG QTY FOR 4CKT EC NO: S2010-0556 DRWN:ATSEE 2010/01/12 CHKD:SKANG 2010/01/14 APPR:MLONG 2010/01/14	REV DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	C-GRID PCB CONN DR HORZ
			$\nabla_A=0$	mm INCH	MM ONLY	NTS	METRIC		
			$\nabla_C=0$	4 PLACES ± --- ± ---	DRAWN BY DATE	TITLE			
			$\nabla_B=0$	3 PLACES ± --- ± ---	DB 1987/07/14	MATERIAL NO. DOCUMENT NO.			
			2 PLACES ± 0.20 ± .008	CHECKED BY DATE	MOLEX INCORPORATED				
			1 PLACE ± --- ± ---	APPROVED BY DATE	SDA-90152				
			ANGULAR ± 2 °	MLONG 2010/01/14	SEE TABLE				
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
				A3					

PART NUMBER	CKT. SIZE	PIN VOID	KINKED PINS	NO. PER TUBE
90152-6234	2 X 17	21	NONE	12
90152-5242	2 X 21	5	NONE	10
90152-7130	2 X 15	NONE	1,2 & 29,30	14

TERMINAL RETENTION FEATURE



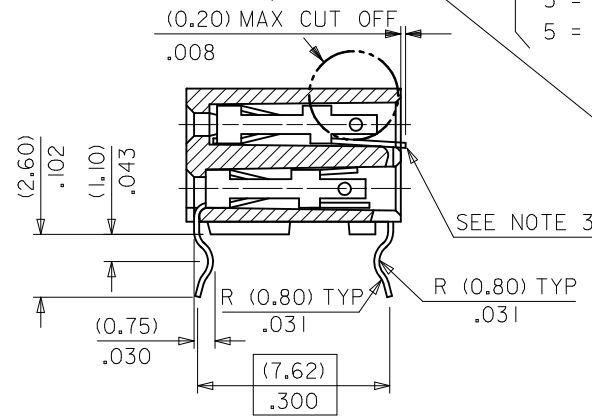
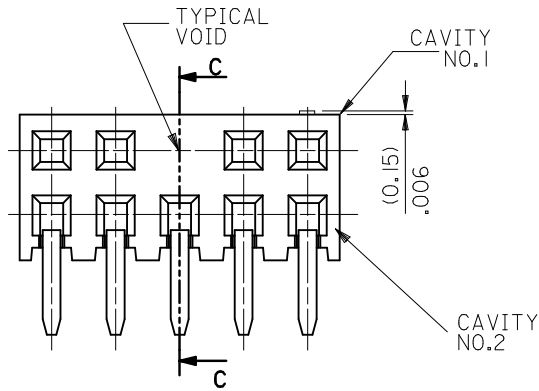
NOTES

- 1) FOR DIMENSIONS SEE SHEET 1.
- 2) THIS MARK INDICATES CIRCUIT NO.1.
- 3) SOLDER TAIL OF TERMINAL IN VOIDED CAVITY MUST BE CROPPED AS SHOWN OR TERMINAL REMOVED.

90152-XXYY

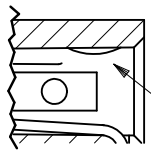
- INDICATES NO. OF CIRCUITS.
- PLATING CODE.
- 1 = VERSION A.
- 2 = VERSION E.
- 3 = VERSION F.
- 5 = VERSION G.

SEE DETAIL "A"



- OPTIONS
- 2 = REGULAR
- 3 = KINKED
- 5 = VOIDS
- 6 = KINKS & VOIDS
- 7 = SELECTIVE KINKS

DETAIL "A"



TERMINAL RETENTION FEATURE

CHG PKG QTY FOR 4CKT EC NO: S2010-0556 DRWN:ATSEE 2010/01/12 CHKD:SKANG 2010/01/14 APPR:MLONG 2010/01/14	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
		$F_A=0$ $F_C=0$ $F_P=0$	mm	INCH	MM ONLY		NTS	METRIC			
B	REV		4 PLACES	± ---	± ---	DRAWN BY	DATE	TITLE			
			3 PLACES	± ---	± ---	CHECKED BY	DATE	C-GRID PCB CONN DR HORZ			
			2 PLACES	± 0.20	± .008	APPROVED BY	DATE	MOLEX INCORPORATED			
			1 PLACE	± ---	± ---	MLONG	2010/01/14	DOCUMENT NO. SDA-90152			
			ANGULAR ± 2 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SDA-90152		5 OF 5		
					SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
					A3						

SEE CHART  
SDA-90152

PART NO.	NO. OF CKTS.	DIM. A		DIM. B $\begin{matrix} (+0.00 \\ -0.30 \\ +.000 \\ -.012 \end{matrix}$		NO. PER TUBE
90152-XX04	4	( 2.54 )	.100	( 5.08 )	.200	110
▲ ▲ 06	6	( 5.08 )	.200	( 7.62 )	.300	73
08	8	( 7.62 )	.300	(10.16)	.400	55
10	10	(10.16)	.400	(12.70)	.500	44
12	12	(12.70)	.500	(15.24)	.600	36
14	14	(15.24)	.600	(17.78)	.700	31
16	16	(17.78)	.700	(20.32)	.800	27
18	18	(20.32)	.800	(22.86)	.900	24
20	20	(22.86)	.900	(25.40)	1.000	22
22	22					20
24	24	(27.94)	1.100	(30.48)	1.200	18
26	26	(30.48)	1.200	(33.02)	1.300	16
28	28					14
30	30	(35.56)	1.400	(38.10)	1.500	14
32	32					13
34	34	(40.64)	1.600	(43.18)	1.700	12
36	36	(43.18)	1.700	(45.72)	1.800	12
38	38	(45.72)	1.800	(48.26)	1.900	11
40	40	(48.26)	1.900	(50.80)	2.000	11
42	42					10
44	44	(53.34)	2.100	(55.88)	2.200	10
46	46					10
48	48					9
50	50	(60.96)	2.400	(63.50)	2.500	8
52	52					8
54	54					8
56	56	(68.58)	2.700	(71.12)	2.800	7
58	58					7
60	60	(73.66)	2.900	(76.20)	3.000	7
▼ ▼ 62	62					6
90152-XX64	64	(78.74)	3.100	(81.28)	3.200	5

PLATING VERSION A

PRE-PLATED HOT DIP TIN  
1.0 TO 2.5 microns (.00004" TO .00010").

PLATING VERSION E

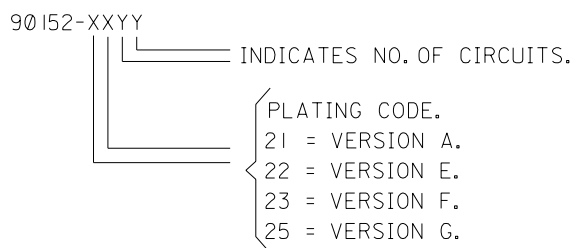
1.27 TO 1.78 microns (.00005" TO .00007") NICKEL  
OVERALL, 0.38 TO 0.64 microns (.000015" TO .000025")  
GOLD ON CONTACT AREA (OVER NICKEL).  
3 TO 5 microns (.00012" TO .00020") TIN  
ON SOLDER TAILS (OVER NICKEL).

PLATING VERSION F.

1.27 TO 1.78 microns (.00005" TO .00007") NICKEL  
OVERALL, 0.76 TO 1.0 microns (.00003" TO .00004")  
GOLD ON CONTACT AREA (OVER NICKEL).  
3 TO 5 microns (.00012" TO .00020") TIN  
ON SOLDER TAILS (OVER NICKEL).

PLATING VERSION G.

1.27 TO 1.78 microns (.00005" TO .00007") NICKEL  
OVERALL, 0.125 TO 0.20 microns (.000005" TO .0000079")  
GOLD ON CONTACT AREA (OVER NICKEL).  
3 TO 5 microns (.00012" TO .00020") TIN  
ON SOLDER TAILS (OVER NICKEL).



STANDARD PRODUCTS

FOR PREVIOUS DRAWING ISSUES SEE MRI.

LEAD FREE CONVERSION NEW BORDER ADDED  
EC NO. E2004-0610  
DRWN: PSHEAHAN 08/01/2004  
CHK: APPR:  
AD

QUALITY SYMBOLS  
MAJOR  
CRITICAL  
REV DESCRIPTION

GENERAL TOLERANCES: (UNLESS SPECIFIED)  
SCALE 5:1  
DESIGN UNITS  mm  INCH  
DRAWN BY & DATE DB 14/ 7/87  
CHECKED BY & DATE  
APPROVED BY & DATE  
CAD FILENAME s90152x2 DGN  
MATERIAL NO. SEE CHART  
DRAWING NO. SDA-90152  
SHEET NO. 20F

DIMENSIONS:  mm  INCH  mm  INCH ONLY  
SHT REV  
REVISION ON CAD ONLY  
TITLE: C-GRID III DUAL ROW HORIZONTAL P.C. BOARD CONNECTOR  
moLEX MOLEX INCORPORATED  
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